

SMD Power Inductor

HPC8040NF-680M

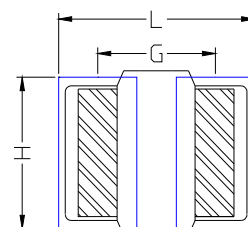
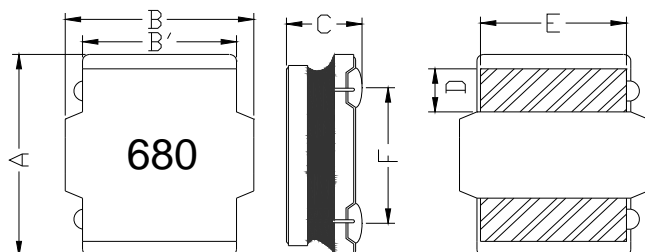
1. Features

1. This specification applies Low Profile Power Inductors.
2. 100% Lead(Pb) & Halogen-Free and RoHS compliant.



2. Dimension

Recommend Land pattern



Series	A(mm)	B(mm)	B'(mm)	C(mm)	D(mm)	E(mm)	F(mm)
HPC8040NF	8.0±0.3	8.0±0.3	6.3±0.2	3.7±0.3	2.0±0.3	6.0±0.3	5.5±0.3

L(mm)	G(mm)	H(mm)
8.5	5.5	6.3

3. Part Numbering

HPC	8040	NF	-	680	M
A	B	C		D	E

A: Series

B: Dimension

C: Type

D: Inductance

E: Inductance Tolerance

A/B°C

680=68.0uH

M=±20%

marking direction cannot decide polarity. Color: Black, unidirectional magnetic shielding

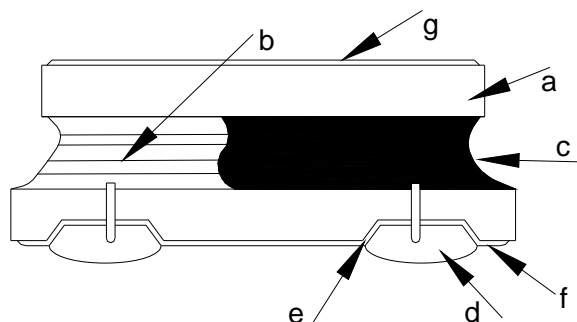
4. Specification

Part Number	Inductance L0 (uH) @ 0 A	Tolerance	Rated current				DCR (mΩ) @25℃
			Tempetature current I rms (A)		Saturation current I sat (A)		
			Typ	Max	Typ	Max	±20%.
HPC8040NF-680M	68.0	±20%	1.65	1.50	1.75	1.50	205

Note:

1. All test data referenced to 25°C ambient, Ls:1MHz/1V.
2. Testing Instrument : HP4284A, CH11025, CH3302, CH1320, CH1320S LCR METER / Rdc:CH502BC MICRO OHMMETER.
3. Heat Rated Current (Irms) will cause the coil temperature rise approximately Δt of 40°C (keep 1min.).
4. Saturation Current (Isat) will cause L0 to drop 30% typical. (keep quickly).
5. The part temperature (ambient + temp rise) should not exceed 125°C under worst case operating conditions. Circuit design, component, PCB trace size and thickness, airflow and other cooling provisions all affect the part temperature. Part temperature should be verified in the end application.
6. Special inquiries besides the above common used types can be met on your requirement.

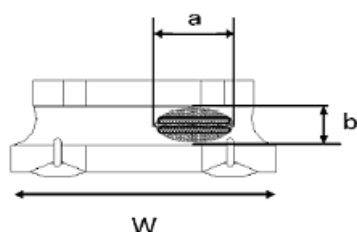
5. Material List



NO	Items	Materials
a	Core	Ferrite Core
b	Wire	Enameled Copper Wire
c	Glue	Epoxy with magnetic powder
d	Terminal	Lead free-Sn Solder
e	Adhesive	Epoxy
f	Copper foil	Pure Copper
g	Ink	Halogen-free ketone

Void appearance tolerance Limit

Size of voids occurring to coating resin is specified below.



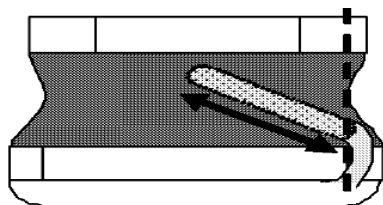
Exposed wire tolerance limit of coating resin part on product side.

Size of exposed wire occurring to coating resin is specified below.

1. Width direction (dimension a) : Acceptable when $a \leq w/2$
Nonconforming when $a > w/2$
2. Length direction (dimension b) : Dimension b is not specified.
3. The total area of exposed wire occurring to each sides is not greater than 50% of coating resin area, and is acceptable.

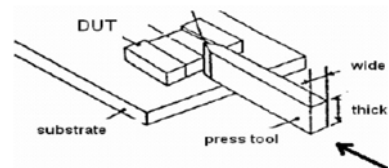
External appearance criterion for exposed wire

Exposed end of the winding wire at the secondary side should be 3mm and below.



6. Reliability and Test Condition

Item	Performance	Test Condition
Operating temperature	-40~+125℃ (Including self - temperature rise)	
Storage temperature	1. -10~+40℃, 50~60%RH (Product without taping) 2. -40~+125℃ (on board)	
Electrical Performance Test		
Inductance	Refer to standard electrical characteristics list.	HP4284A, CH11025, CH3302, CH1320, CH1320S LCR Meter.
DCR		CH16502, Agilent33420A Micro-Ohm Meter.
Saturation Current (Isat)	Approximately ΔL 30%	Saturation DC Current (Isat) will cause L0 to drop ΔL (%).
Heat Rated Current (Irms)	Approximately ΔT 40℃	Heat Rated Current (Irms) will cause the coil temperature rise ΔT (℃). 1. Applied the allowed DC current 2. Temperature measured by digital surface thermometer
Reliability Test		
Life Test	Appearance : No damage. Inductance : within $\pm 10\%$ of initial value Q : Shall not exceed the specification value. RDC : within $\pm 15\%$ of initial value and shall not exceed the specification value	Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020D Classification Reflow Profiles) Temperature : 125 ± 2 ℃ (Inductor) Applied current : rated current Duration : 1000 ± 12 hrs Measured at room temperature after placing for 24 ± 2 hrs
Load Humidity		Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020D Classification Reflow Profiles) Humidity : 85 $\pm 2\%$ R.H. Temperature : 85℃ ± 2 ℃ Duration : 1000hrs Min. with 100% rated current Measured at room temperature after placing for 24 ± 2 hrs
Moisture Resistance		Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020D Classification Reflow Profiles) 1. Baked at 50℃ for 25hrs, measured at room temperature after placing for 4 hrs. 2. Raise temperature to 65 ± 2 ℃ 90-100%RH in 2.5hrs, and keep 3 hours, cool down to 25℃ in 2.5hrs. 3. Raise temperature to 65 ± 2 ℃ 90-100%RH in 2.5hrs, and keep 3 hours, cool down to 25℃ in 2.5hrs, keep at 25℃ for 2 hrs then keep at -10℃ for 3 hrs 4. Keep at 25℃ 80-100%RH for 15min and vibrate at the frequency of 10 to 55 Hz to 10 Hz, measure at room temperature after placing for 1~2 hrs.
Thermal shock		Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020D Classification Reflow Profiles) Condition for 1 cycle Step1 : -40 ± 2 ℃ 30 ± 5 min Step2 : 25 ± 2 ℃ ≤ 0.5 min Step3 : 125 ± 2 ℃ 30 ± 5 min Number of cycles : 500 Measured at room temperature after placing for 24 ± 2 hrs
Vibration		Oscillation Frequency: 10~2K~10Hz for 20 minutes Equipment : Vibration checker Total Amplitude: 1.52mm $\pm 10\%$ Testing Time : 12 hours(20 minutes, 12 cycles each of 3 orientations) °

Item	Performance	Test Condition														
Bending	Appearance : No damage. Impedance : within±15% of initial value Inductance : within±10% of initial value Q : Shall not exceed the specification value. RDC : within ±15% of initial value and shall not exceed the specification value	Shall be mounted on a FR4 substrate of the following dimensions: >=0805 inch(2012mm):40x100x1.2mm <0805 inch(2012mm):40x100x0.8mm Bending depth: >=0805 inch(2012mm):1.2mm <0805 inch(2012mm):0.8mm duration of 10 sec.														
Shock		<table><tr><th>Type</th><th>Peak value (g's)</th><th>Normal duration (D) (ms)</th><th>Wave form</th><th>Velocity change (Vi)ft/sec</th></tr><tr><td>SMD</td><td>50</td><td>11</td><td>Half-sine</td><td>11.3</td></tr><tr><td>Lead</td><td>50</td><td>11</td><td>Half-sine</td><td>11.3</td></tr></table>	Type	Peak value (g's)	Normal duration (D) (ms)	Wave form	Velocity change (Vi)ft/sec	SMD	50	11	Half-sine	11.3	Lead	50	11	Half-sine
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SMD	50	11	Half-sine	11.3												
Lead	50	11	Half-sine	11.3												
Solder ability	More than 95% of the terminal electrode should be covered with solder ◦	Preheat: 150℃,60sec. ◦ Solder: Sn96.5% Ag3% Cu0.5% Temperature: 245±5℃ ◦ Flux for lead free: Rosin. 9.5% ◦ Dip time: 4±1sec ◦ Depth: completely cover the termination														
Resistance to Soldering Heat		Depth: completely cover the termination <table><tr><th>Temperature(℃)</th><th>Time(s)</th><th>Temperature ramp/immersion and emersion rate</th><th>Number of heat cycles</th></tr><tr><td>260 ±5 (solder temp)</td><td>10 ±1</td><td>25mm/s ±6 mm/s</td><td>1</td></tr></table>	Temperature(℃)	Time(s)	Temperature ramp/immersion and emersion rate	Number of heat cycles	260 ±5 (solder temp)	10 ±1	25mm/s ±6 mm/s	1						
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260 ±5 (solder temp)	10 ±1	25mm/s ±6 mm/s	1													
Terminal Strength	Appearance : No damage. Impedance : within±15% of initial value Inductance : within±10% of initial value Q : Shall not exceed the specification value. RDC : within ±15% of initial value and shall not exceed the specification value e	Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020DClassification Reflow Profiles With the component mounted on a PCB with the device to be tested, apply a force(>0805:1kg , <=0805:0.5kg)to the side of a device being tested. This force shall be applied for 60 +1 seconds. Also the force shall be applied gradually as not to apply a shock to the component being tested. 														

Note : When there are questions concerning measurement result : measurement shall be made after 48 \pm 2 hours of recovery under the standard condition.

7 Soldering and Mounting

(1) Soldering

Mildly activated rosin fluxes are preferred. The minimum amount of solder can lead to damage from the stresses caused by the difference in coefficients of expansion between solder, chip and substrate. TAI-TECH terminations are suitable for re-flow soldering systems. If hand soldering cannot be avoided, the preferred technique is the utilization of hot air soldering tools.

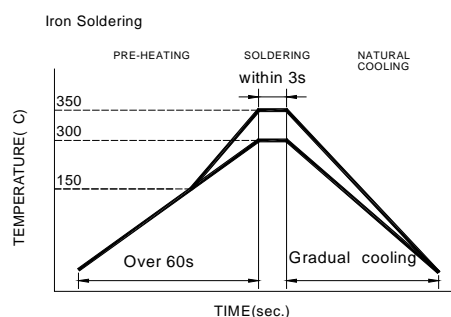
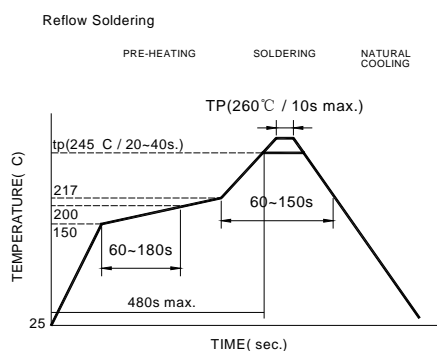
(2) Solder re-flow:

Recommended temperature profiles for re-flow soldering in Figure 1.

(3) Soldering Iron:

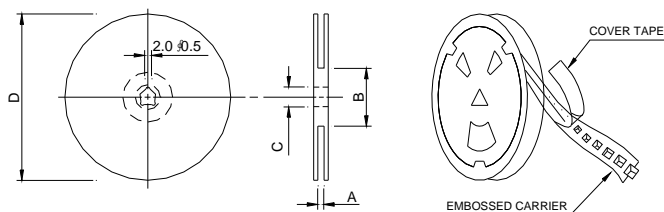
Products attachment with a soldering iron is discouraged due to the inherent process control limitations. In the event that a soldering iron must be employed the following precautions are recommended.

- Preheat circuit and products to 150°C
- Never contact the ceramic with the iron tip
- Use a 20 watt soldering iron with tip diameter of 1.0mm
- 355°C tip temperature (max)
- 1.0mm tip diameter (max)
- Limit soldering time to 4~5sec.



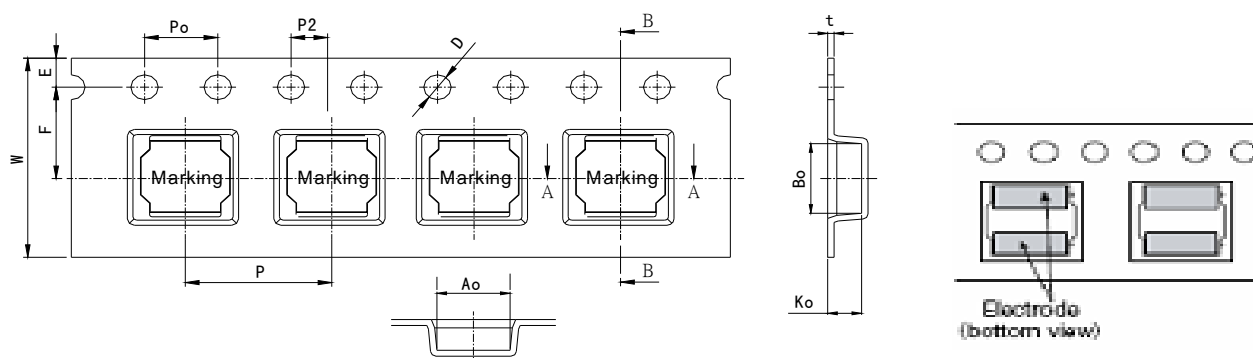
8. Packaging Information

(1) Reel Dimension



Type	A(mm)	B(mm)	C(mm)	D(mm)
13"x16mm	16.4+2/-0	80±2.0	13+0.5/-0.2	330±3.0

(2) Tape Dimension

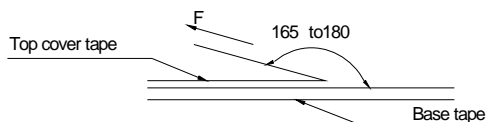


Series	Size	Bo(mm)	Ao(mm)	Ko(mm)	P(mm)	w(mm)	t(mm)	Emm	F(mm)	D(mm)	Po(mm)	P2(mm)
HPC	8040	8.4±0.1	8.4±0.1	4.3±0.1	12±0.1	16±0.3	0.4±0.1	1.75±0.1	7.5±0.1	1.5±0.1	4.0±0.1	2.00±0.1

(3) Packaging Quantity

HPC	8040
Reel	1000
Inner box	2000
Carton	8000

(4) Tearing Off Force



The force for tearing off cover tape is 10 to 130 grams in the arrow direction under the following conditions(referenced ANSI/EIA-481-C-2003 of 4.11 standard).

Room Temp. (°C)	Room Humidity (%)	Room atm (hPa)	Tearing Speed mm/min
5~35	45~85	860~1060	300

Application Notice

- Storage Conditions
To maintain the solderability of terminal electrodes:
 - TAI-TECH products meet IPC/JEDEC J-STD-020D standard-MSL, level 1.
 - Temperature and humidity conditions: Less than 40°C and 60% RH.
 - Recommended products should be used within 12 months from the time of delivery.
 - The packaging material should be kept where no chlorine or sulfur exists in the air.
- Transportation
 - Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
 - The use of tweezers or vacuum pick up is strongly recommended for individual components.
 - Bulk handling should ensure that abrasion and mechanical shock are minimized.

9. Typical Performance Curves

